

Guidelines for SISPAD 2026

1st Given Name Surname
Department name (of Affilication)
Organization name (of Affilication)
 City, Country
 Email address

2nd Given Name Surname
Department name (of Affilication)
Organization name (of Affilication)
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 Email address

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Abstract—This document is a “live” template and instructions for L^AT_EX. This and the IEEEtran.cls file define the components of your paper [title, text, headings, etc.].

Index Terms—component, formatting, style, styling, insert.

I. INTRODUCTION

This document is a proposed template and guideline for SISPAD 2026. It is based on IEEE template example. For more details, please refer to the IEEE template example available at <https://www.ieee.org/conferences/publishing/templates.html>.

II. SISPAD2026

The International Conference on Simulation of Semiconductor Processes and Devices (SISPAD) [1] provides an international forum for the presentation of leading-edge research and development results in the area of process and device simulation. SISPAD is one of the longest-running conferences devoted to technology computer-aided design (TCAD) and advanced modeling of novel semiconductor devices and nano electronic structures. SISPAD 2026 will be held in-person in Kumamoto, Japan, from September 28 to 30, 2026.

A satellite workshop will be offered on the day before the main conference starts (September 27).

We hope to see you in Kumamoto, Japan in September.

III. PRESENTATION TYPE AND REQUIREMENTS

A. Presentation type

SISPAD 2026 will be held in-person and accepts oral and poster presentations.

Final determination of the presentation type will be made by the Technical Program Committee.

B. Requirements

- Deadline for submission: <https://sispad2026.jp/>
- All abstracts must be written in English.
- Please prepare the abstract in two pages (A4 portrait, including tables and figures), and the file size must be less than 10 MB.
- A font size between 10 and 12 points is suggested.
- Abstracts sent by e-mail or postal mail will NOT be considered. Please submit your abstracts using our online submission portal at <https://sispad2026.jp/>.

Identify applicable funding agency here. If none, delete this.

- You can NOT use two-byte fonts like Japanese, Korean, Chinese characters or single-byte Asian fonts such as MS Gothic, MS Mincho, Ryumin, or Batang.

IV. FULL SUBMISSION INFORMATION

Full submission information will be posted on the conference website [1].

A Camera-ready copy of a four-page manuscript will be required from the authors for inclusion in the Conference Proceedings by June 30, 2026.

Since notification of acceptance and further announcements will be sent only to the abstract submitter’s registered email address, we strongly recommend each presenting author to create his/her own account and submit his/her abstract(s) from that account.

REFERENCES

- [1] SISPAD Committee, “SISPAD Website”. [Online]. Available: <https://sispad2026.jp/>



Fig. 1. Example of a figure caption.